

36. The gel material of claim 32, wherein the at least one rubber compound comprises at least one saturated compound.
37. The gel material of claim 36, wherein the at least one rubber compound comprises hydrogenated polyalkyldiene mono-ol, hydrogenated polyalkyldiene diol, or a combination or mixture thereof.
38. The gel material of claim 37, wherein the hydrogenated polyalkyldiene mono-ol comprises hydrogenated polybutadiene mono-ol.
39. The gel material of claim 37, wherein the hydrogenated polyalkyldiene diol comprises hydrogenated polybutadiene diol.
40. The gel material of claim 32, wherein the at least one amine resin comprises a melamine resin.
41. The gel material of claim 40, wherein the melamine resin comprises an alkylated melamine resin.
42. The gel material of claim 41, wherein the alkylated melamine resin comprises butylated melamine resin.
43. The gel material of claim 32, wherein the at least one thermally conductive filler comprises a metal powder, a boron nitride compound or a combination or mixture thereof.
44. The gel material of claim 43, wherein the metal powder comprises aluminum powder, silver powder, copper powder or a combination or mixture thereof.
45. The gel material of claim 34, wherein the at least one phase change material comprises a wax.
46. The gel material of claim 45, wherein the wax comprises a paraffin wax.
47. The gel material of claim 32, further comprising at least one catalytic material.

48. The gel material of claim 34, further comprising at least one catalytic material.
49. The gel material of one of claims 47 or 48, wherein the at least one catalytic material comprise sulfonic acid catalyst.
50. The gel material of one of claims 32 or 34, further comprising at least one wetting agent.
51. The gel material of claim 50, wherein the wetting agent comprises organotitanate.
52. A layered component comprising the gel material of claim 32.
53. An electronic component comprising the gel material of claim 32.
54. A layered component comprising the gel material of claim 34.
55. An electronic component comprising the gel material of claim 34.
56. A liquid composition comprising the gel material of claim 32.
57. A solid composition comprising the gel material of claim 34.
58. A tape comprising the gel material of claim 34.

#### **IN THE SPECIFICATION**

Insert the following before "Field of the Invention":

This application is a divisional of allowed application Serial Number 10/047,617, filed January 14, 2002.

#### **REMARKS**

No new matter was added by this preliminary amendment.

Please use JM36365 CIP/DIV - 4962 as the docket number for this application.

**REQUEST FOR ALLOWANCE**

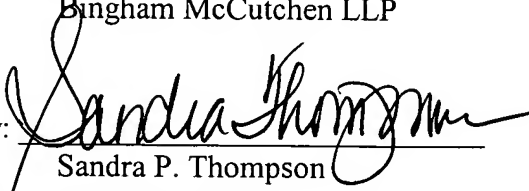
Claims 32-58 are pending in this application. The applicants request allowance of all pending claims.

Respectfully submitted,

Bingham McCutchen LLP

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By:

  
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